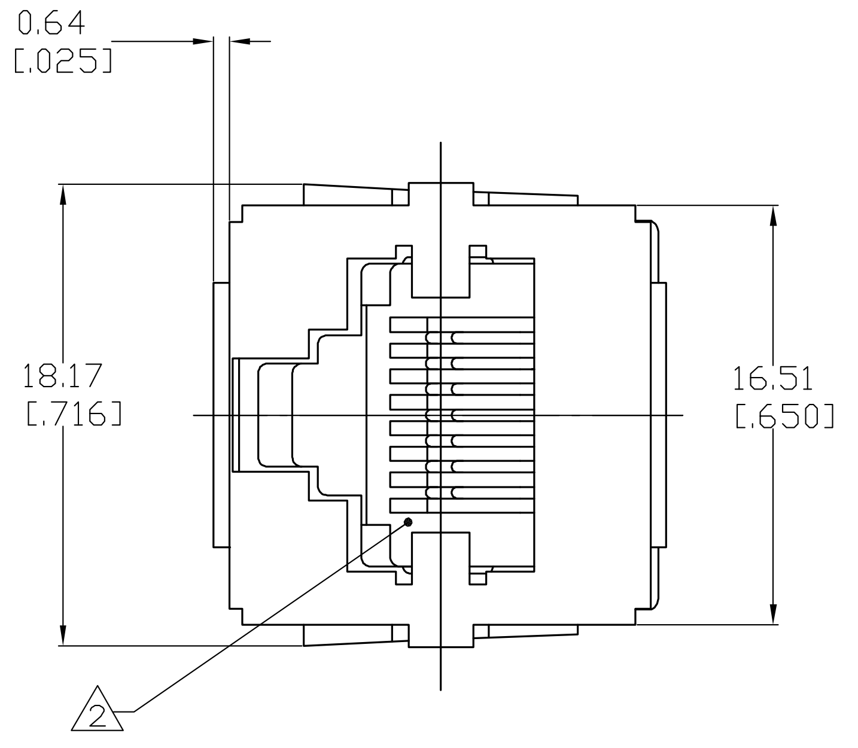
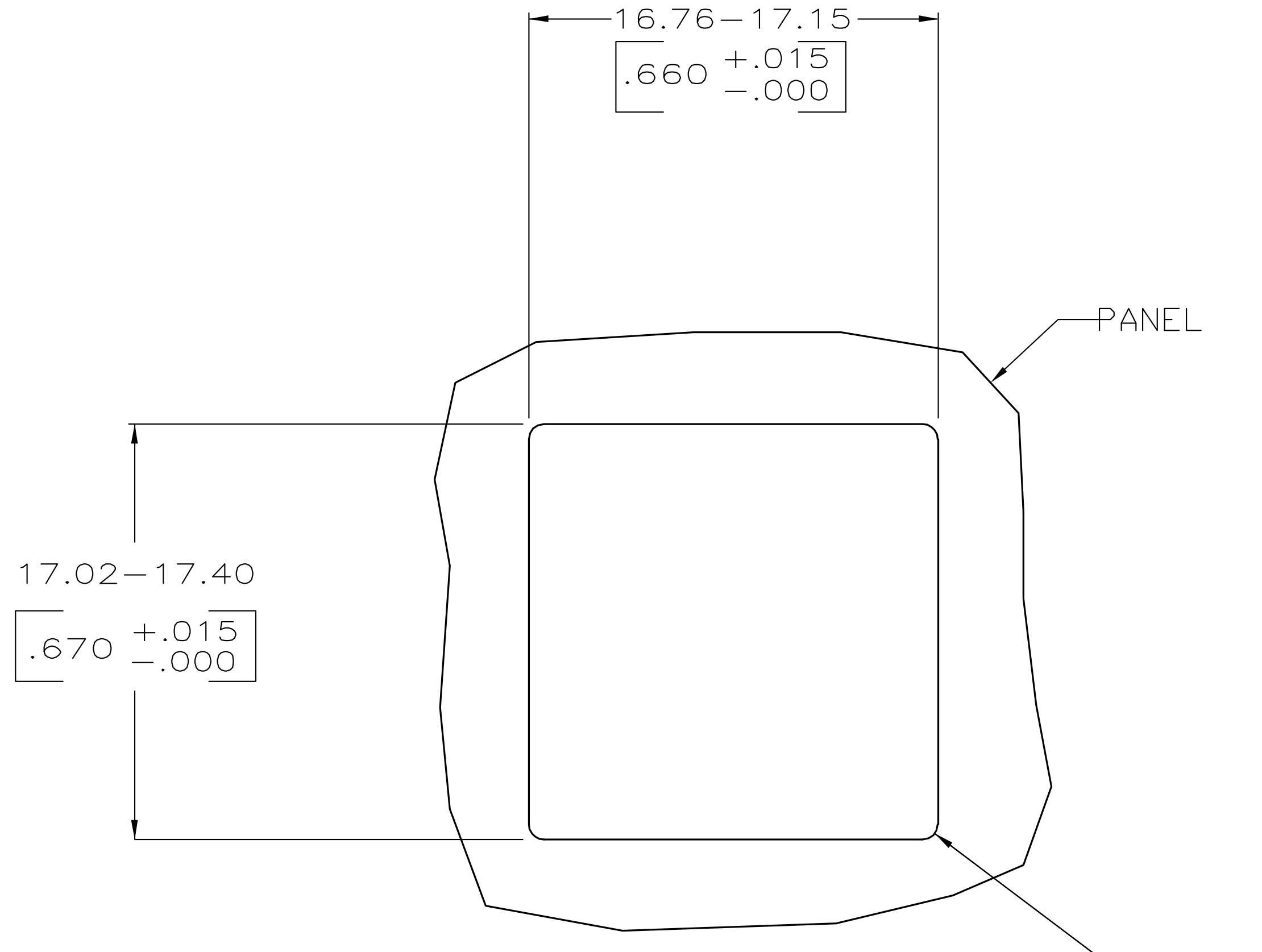
LOC	DIST
AA	00

REVISIONS

P	LTR	DESCRIPTION	DATE	DWN	APVD
	E	ECO-06-001942	27JAN06	LAM	MY

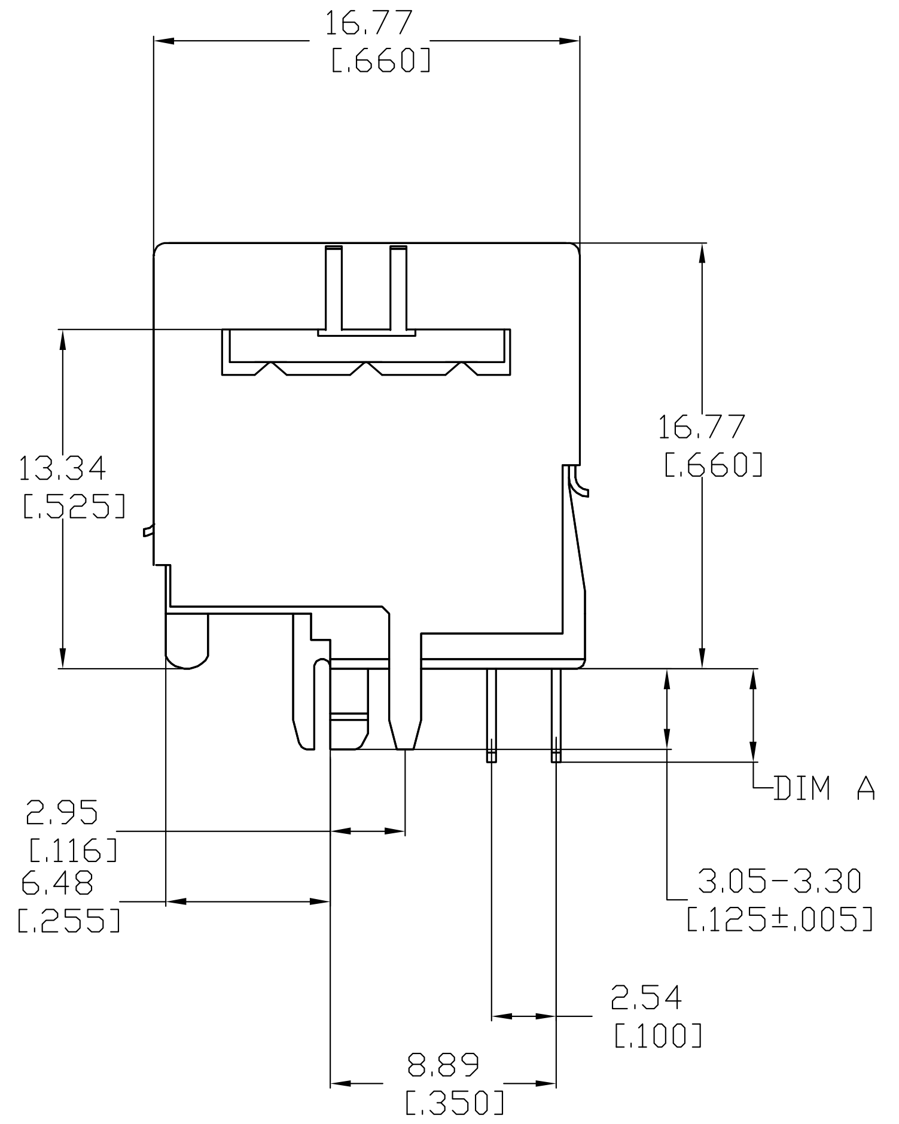


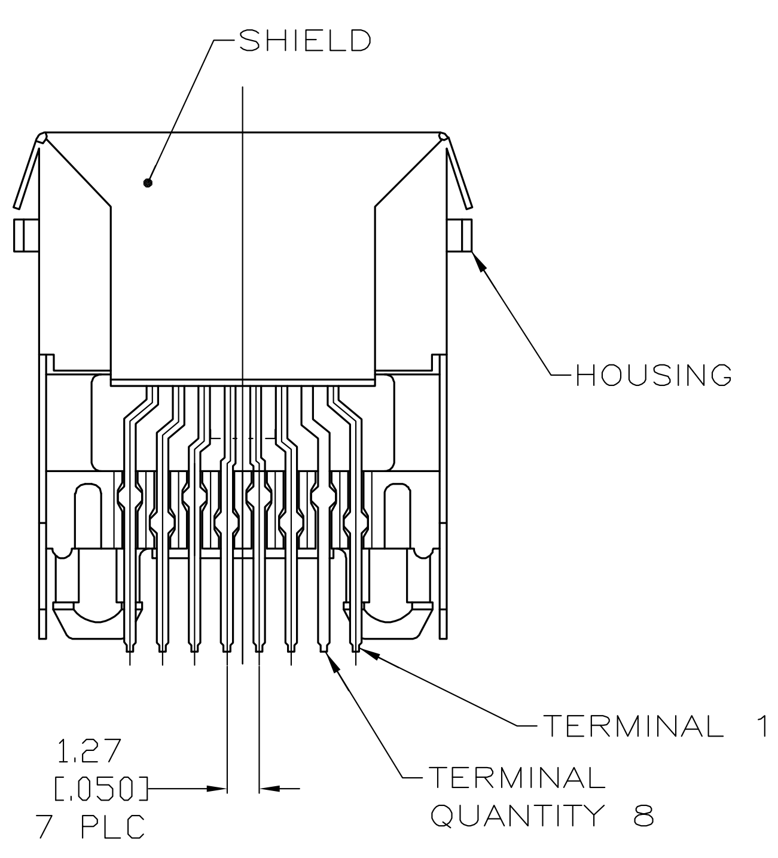


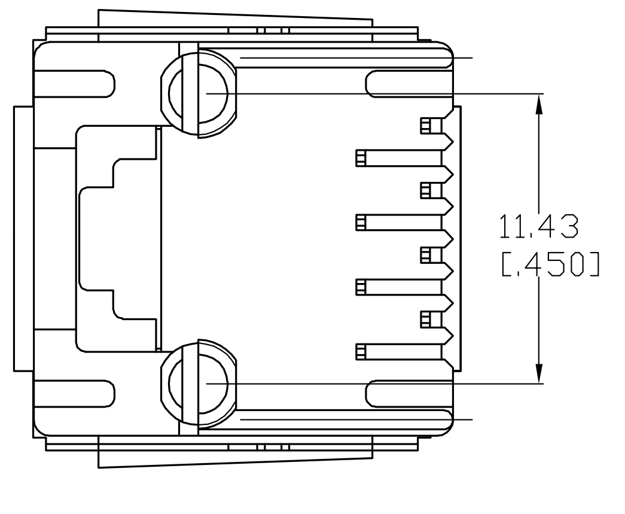
SUGGESTED PANEL
CUTOUT

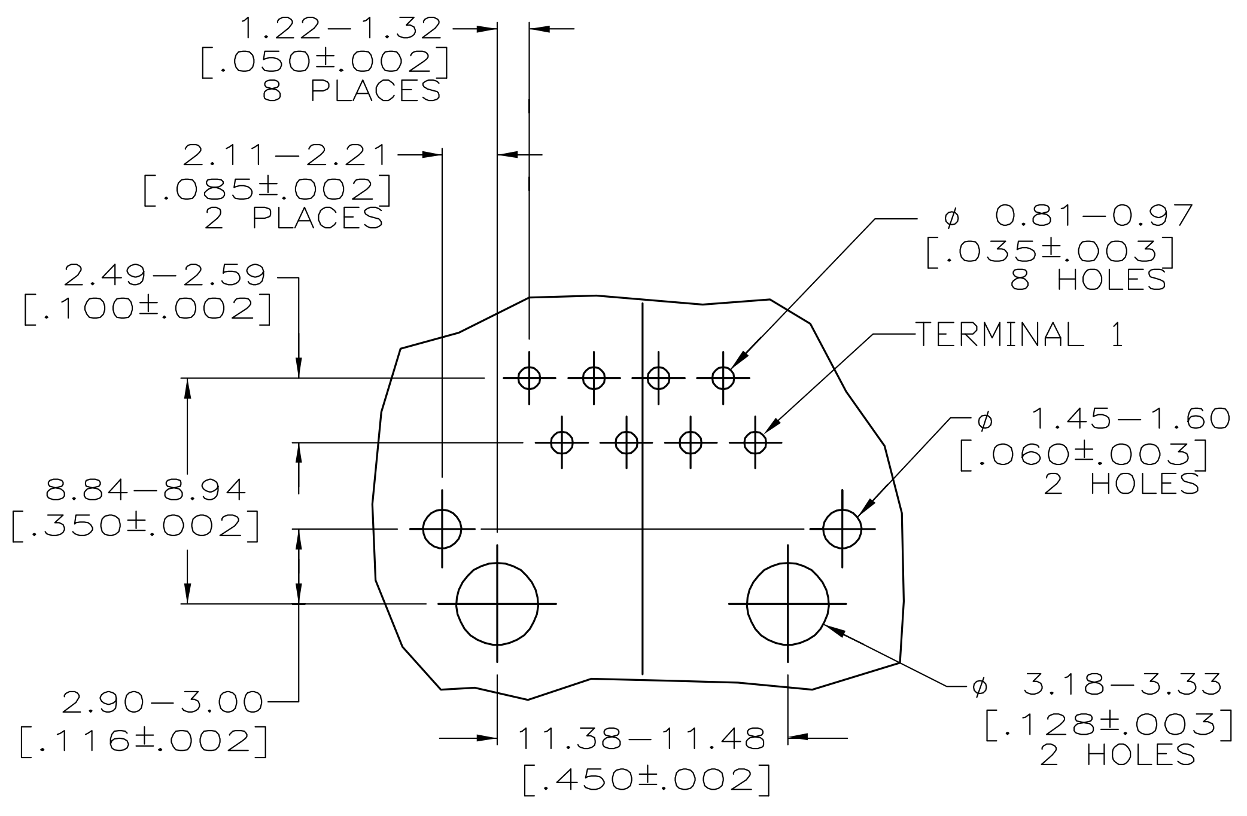
1. MATERIAL: HOUSING– POLYESTER MOLDING COMPOUND, BLACK.
TERMINALS– 0.350 [.0138] THICK PHOS BRONZE PLATED WITH 1.27μm [.000050] MINIMUM THICK GOLD IN LOCALIZED AREA AND 3.81μm [.000150] MINIMUM THICK TIN–LEAD IN SOLDER AREA OVER 1.27μm [.000050] MINIMUM THICK NICKEL UNDERPLATE
SHIELD– COPPER ZINC ALLOY PLATED WITH 2.03μm [.000080] MINIMUM THICK TIN–LEAD OVER 2.54μm [.000100] MINIMUM THICK COPPER UNDERPLATE.

2. CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLITIN 345–81, PE–76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.









SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
NONCOMPONENT SIDE DOWN

DIM A	PART NUMBER
2.79–3.30 [.120±.010]	557696–2
2.92–3.94 [.135±.020]	557969–1

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm

TOLERANCES UNLESS OTHERWISE SPECIFIED:
0 PLC ± –
1 PLC ± –
2 PLC ± 0.13[.005]
3 PLC ± –
4 PLC ± –
ANGLES ± –

MATERIAL: SEE NOTE 1
FINISH: SEE NOTE 1

DWN B. SIMPSON 6–16–93
CHK B. FOX 6–24–93
APVD S.FLICKINGER 27JAN2006
PRODUCT SPEC 108–1163
APPLICATION SPEC 114–2048
WEIGHT –

tyco Electronics
Tyco Electronics Corporation
Harrisburg, PA 17105–3608

NAME
MODULAR JACK ASSEMBLY,
TOP ENTRY,8 POSITION,
FLANGELESS,SHIELDED,WITH PANEL

SIZE A1
CAGE CODE 00779
DRAWING NO C–557969
RESTRICTED TO –

CUSTOMER DRAWING

SCALE 4:1
SHEET 1 OF 1
REV E